



**EFM101
THRU
EFM107**

**SURFACE MOUNT GLASS PASSIVATED
SUPER FAST SILICON RECTIFIER
VOLTAGE RANGE 50 to 600 Volts CURRENT 1.0 Ampere**

FEATURES

- * Glass passivated device
- * Ideal for surface mounted applications
- * Low leakage current
- * Metallurgically bonded construction
- * Mounting position: Any
- * Weight: 0.057 gram

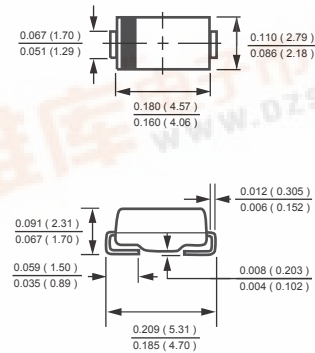
MECHANICAL DATA

- * Epoxy : Device has UL flammability classification 94V-0

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25 °C ambient temperature unless otherwise specified.
Single phase, half wave, 60 Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

DO-214AC



Dimensions in inches and (millimeters)

MAXIMUM RATINGS (@ TA=25 °C unless otherwise noted)

RATINGS	SYMBOL	EFM101	EFM102	EFM103	EFM104	EFM105	EFM106	EFM107	UNITS
Maximum Recurrent Peak Reverse Voltage	V _{RRM}	50	100	150	200	300	400	600	Volts
Maximum RMS Voltage	V _{RMS}	35	70	105	140	210	280	420	Volts
Maximum DC Blocking Voltage	V _{DC}	50	100	150	200	300	400	600	Volts
Maximum Average Forward Rectified Current at T _A = 55°C	I _O	1.0							Amps
Peak Forward Surge Current 8.3 ms single half sine-wave superimposed on rated load (JEDEC method)	I _{FSM}	30							Amps
Typical Thermal Resistance (Note 4)	R _{θJA}	85							°C/W
	R _{θJL}	35							
Typical Junction Capacitance (Note 2)	C _J	15				10			pF
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to + 150							°C

ELECTRICAL CHARACTERISTICS (@ TA=25 °C unless otherwise noted)

CHARACTERISTICS		SYMBOL	EFM101	EFM102	EFM103	EFM104	EFM105	EFM106	EFM107	UNITS
Maximum Instantaneous Forward Voltage at 1.0A DC		V _F	0.95				1.25		1.50	Volts
Maximum DC Reverse Current at Rated DC Blocking Voltage	@T _A = 25°C	I _R	5.0							μAmps
	@T _A = 100°C		100							
Maximum Reverse Recovery Time (Note 1)		t _{rr}	35						50	nSec

NOTES : 1. Reverse Recovery Test Conditions: $I_F = 0.5\text{A}$, $I_R = -1.0\text{A}$, $I_{RR} = -0.25\text{A}$
2. Measured at 1 MHz and applied reverse voltage of 4.0 volts
3. "Fully ROHS compliant", "100% Sn plating (Pb-free)".
4. Thermal Resistance : Mounted on PCB.

2006-11
REV:B

RATING AND CHARACTERISTICS CURVES (EFM101 THRU EFM107)

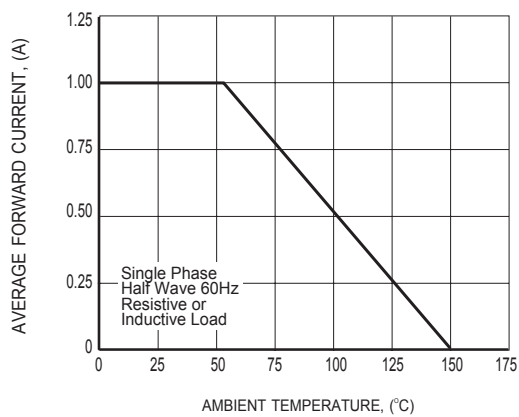
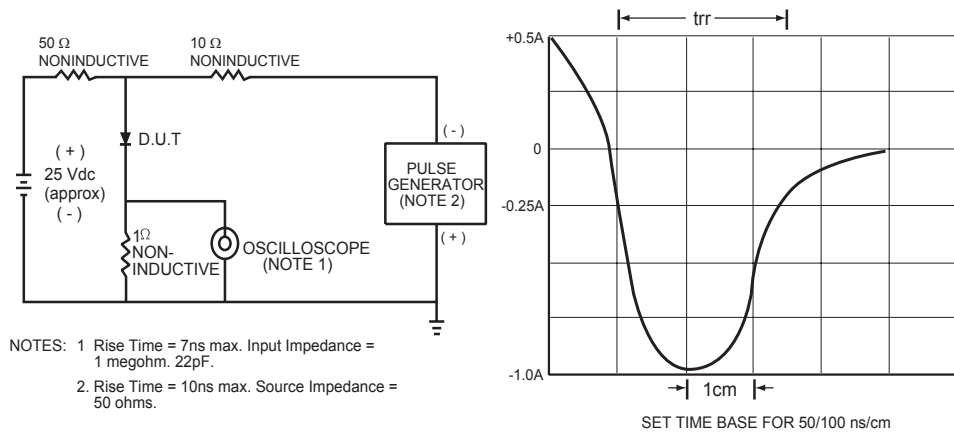


FIG.2 TYPICAL FORWARD CURRENT DERATING CURVE

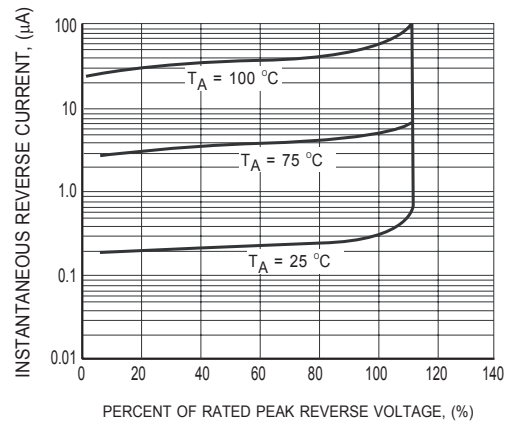


FIG.3 TYPICAL REVERSE CHARACTERISTICS

RATING AND CHARACTERISTICS CURVES (EFM101 THRU EFM107)

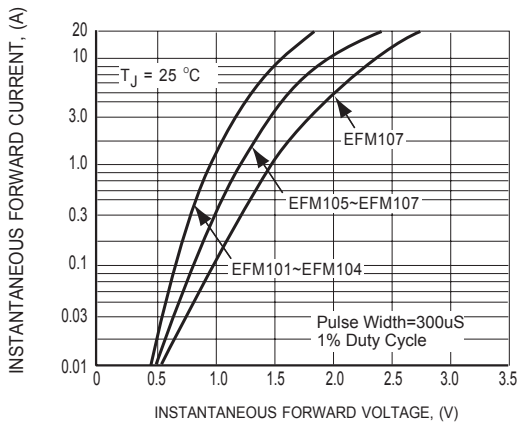


FIG.4 TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

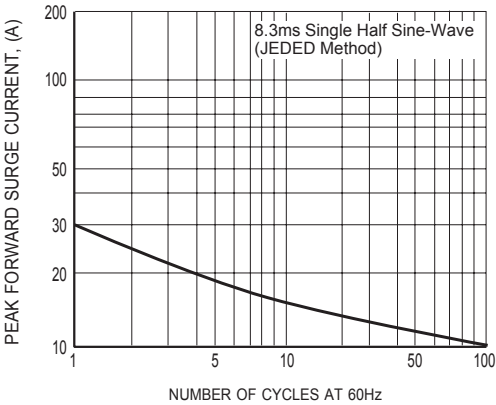


FIG.5 MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

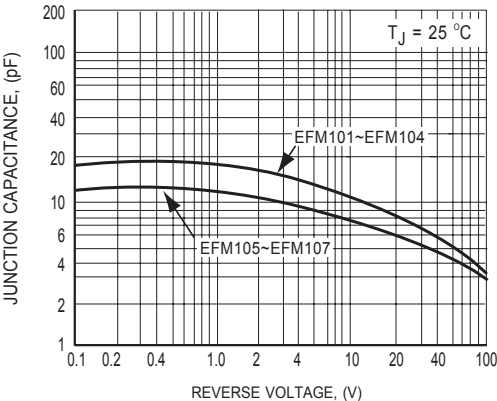
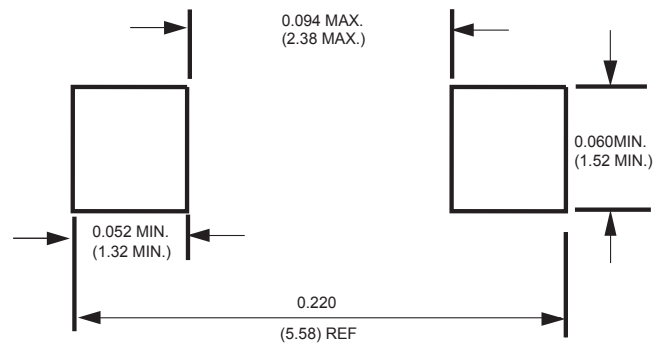


FIG.6 TYPICAL JUNCTION CAPACITANCE

Mounting Pad Layout



Dimensions in inches and (millimeters)

